

# Isc N-Channel MOSFET Transistor

# STP22NM60N

**• FEATURES**

- Low input capacitance and gate charge
- Low gate input resistances
- 100% avalanche tested
- Minimum Lot-to-Lot variations for robust device performance and reliable operation

**• APPLICATIONS**

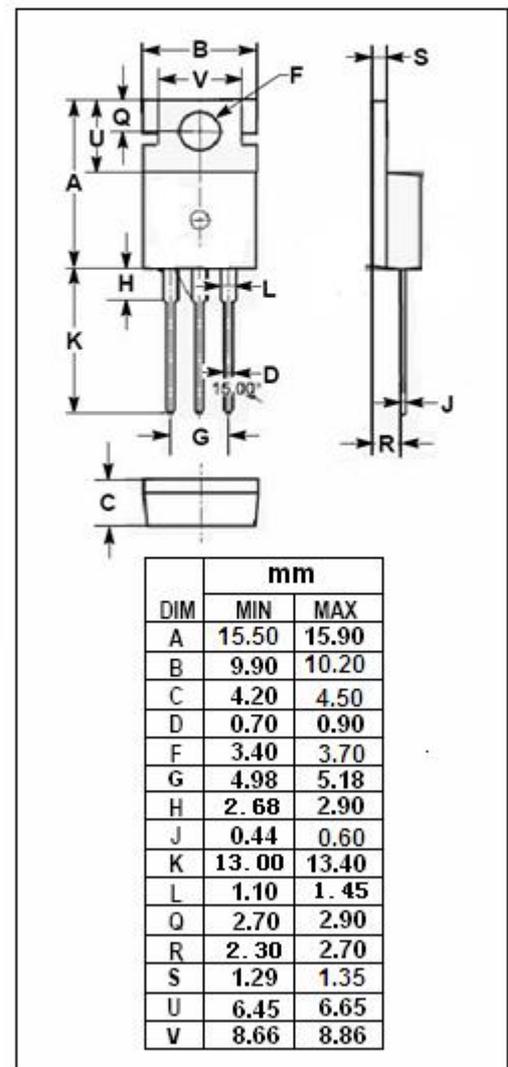
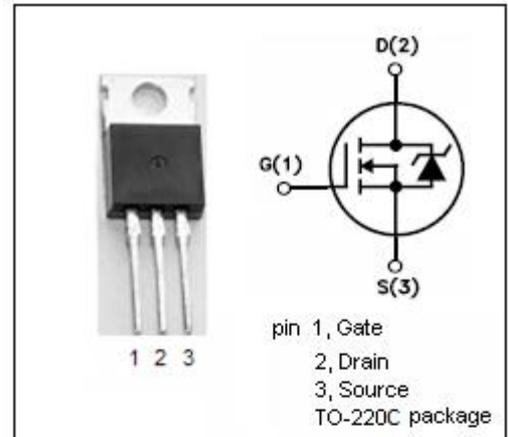
- Switching applications

**• ABSOLUTE MAXIMUM RATINGS(T<sub>a</sub>=25°C)**

SYMBOL	PARAMETER	VALUE	UNIT
V <sub>DSS</sub>	Drain-Source Voltage	600	V
V <sub>GSS</sub>	Gate-Source Voltage	±30	V
I <sub>D</sub>	Drain Current-Continuous@T <sub>c</sub> =25°C T <sub>c</sub> =100°C	16 10	A
I <sub>DM</sub>	Drain Current-Single Pulsed	64	A
P <sub>D</sub>	Total Dissipation	125	W
T <sub>j</sub>	Operating Junction Temperature	-55~150	°C
T <sub>stg</sub>	Storage Temperature	-55~150	°C

**• THERMAL CHARACTERISTICS**

SYMBOL	PARAMETER	MAX	UNIT
Rth(ch-c)	Channel-to-case thermal resistance	1.0	°C/W
Rth(ch-a)	Channel-to-ambient thermal resistance	62.5	°C/W



**Isc N-Channel MOSFET Transistor**
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**ELECTRICAL CHARACTERISTICS**

 T<sub>C</sub>=25°C unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V; I <sub>D</sub> = 1mA	600			V
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =±30V; I <sub>D</sub> =0.25mA	2		4	V
R <sub>DS(on)</sub>	Drain-Source On-Resistance	V <sub>GS</sub> = 10V; I <sub>D</sub> =8A		200	220	mΩ
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> = ±25V; V <sub>DS</sub> = 0V			±0.1	μA
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> = 600V; V <sub>GS</sub> = 0V; T <sub>J</sub> =25°C T <sub>J</sub> =125°C			1 100	μA
V <sub>SDF</sub>	Diode forward voltage	I <sub>SD</sub> =16A, V <sub>GS</sub> = 0 V			1.6	V